

General Description

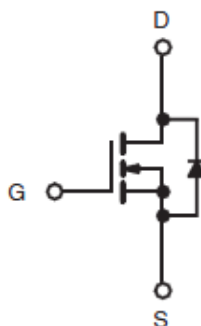
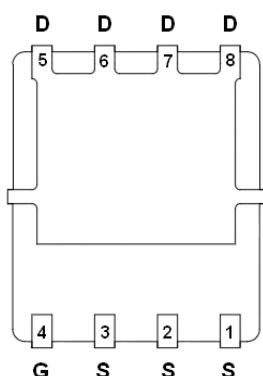
AFN6872S, N-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent $R_{DS(ON)}$, low gate charge.

These devices are particularly suited for low voltage power management, and low in-line power loss are needed in commercial industrial surface mount applications.

Features

- $I_D=20A, R_{DS(ON)}=18m\Omega @ V_{GS}=10V$
- $I_D=15A, R_{DS(ON)}=20m\Omega @ V_{GS}=6V$
- Super high density cell design for extremely low $R_{DS(ON)}$
- DFN5X6-8L package design

Pin Description (DFN5X6-8L)



Application

- Networking / Telecom / Server
- LED Lighting Applications
- Quick Charger Applications
- DC-DC Primary Side Switch

Pin Define

Pin	Symbol	Description
1~3	S	Source
4	G	Gate
5~8	D	Drain

Ordering Information

Part Ordering No.	Part Marking	Package	Unit	Quantity
AFN6872SFN568RG	6872S	DFN5X6-8L	Tape & Reel	2500 EA

※ 6872S : Parts Code

※ YYMMDD : Date Code

※ AFN6872SFN568RG : 13" Tape & Reel ; Pb- Free ; Halogen -Free



Absolute Maximum Ratings

($T_A=25^\circ\text{C}$ Unless otherwise noted)

Parameter	Symbol	Typical	Unit
Drain-Source Voltage	V_{DSS}	150	V
Gate –Source Voltage	V_{GSS}	± 25	V
Continuous Drain Current($T_J=150^\circ\text{C}$)	$T_C=25^\circ\text{C}$	54	A
	$T_C=70^\circ\text{C}$	43	
Pulsed Drain Current ($t=100\mu\text{s}$)	$T_A=25^\circ\text{C}$	13	
	$T_A=70^\circ\text{C}$	10	
Continuous Source Current(Diode Conduction)	I_S	60	A
		5.6	
Single Pulse Avalanche Current	I_{AS}	30	mJ
	E_{AS}	45	
Power Dissipation	$T_C=25^\circ\text{C}$	104	W
	$T_C=75^\circ\text{C}$	66	
	$T_A=25^\circ\text{C}$	6.25	
	$T_A=75^\circ\text{C}$	4.0	
Operating Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55/150	$^\circ\text{C}$
Maximum Junction-to-Ambient	$R_{\theta JA}$	20	$^\circ\text{C}/\text{W}$
Maximum Junction-to-Case (Drain)	$R_{\theta JA}$	1.2	

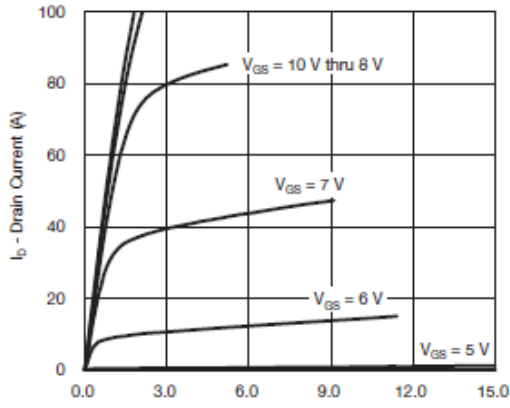
Electrical Characteristics

($T_A=25^\circ\text{C}$ Unless otherwise noted)

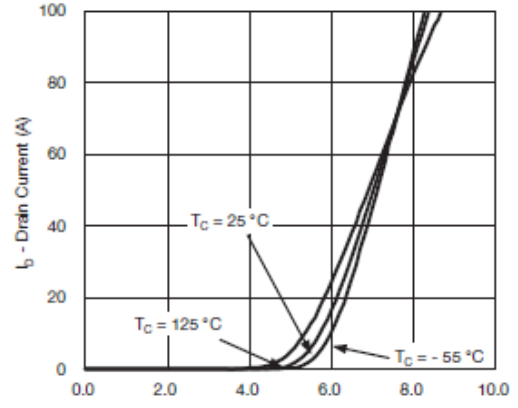
Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu\text{A}$	150			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	2.0	3.0	4.0	
Gate Leakage Current	I_{GSS}	$V_{DS}=0V, V_{GS}=\pm 25V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=120V, V_{GS}=0V$			1	uA
		$V_{DS}=120, V_{GS}=0V$ $T_J=85^\circ\text{C}$			30	
On-State Drain Current	$I_{D(on)}$	$V_{DS} \geq 10V, V_{GS}=10V$	40			A
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=20A$		13	18	m Ω
		$V_{GS}=6V, I_D=15A$		15	20	
Forward Transconductance	g_{FS}	$V_{DS}=10, I_D=20A$		30		S
Diode Forward Voltage	V_{SD}	$I_S=8A, V_{GS}=0V$		0.75	1.3	V
Dynamic						
Total Gate Charge	Q_g	$V_{DS}=75V, V_{GS}=7.5V$ $I_D=20A$		24	40	nC
Gate-Source Charge	Q_{gs}		8			
Gate-Drain Charge	Q_{gd}		10			
Gate Resistance	R_g	$f=1\text{MHz}$	0.3	1.0	2.0	Ω
Input Capacitance	C_{iss}	$V_{DS}=75V, V_{GS}=0V$ $f=1\text{MHz}$		1300		pF
Output Capacitance	C_{oss}		350			
Reverse Transfer Capacitance	C_{rss}		30			
Turn-On Time	$t_{d(on)}$	$V_{DD}=75V, R_L=3.75\Omega$ $I_D=20A, V_{GEN}=10V$ $R_G=1\Omega$		10	20	ns
	t_r			12	24	
Turn-Off Time	$t_{d(off)}$			15	30	
	t_f			7	14	



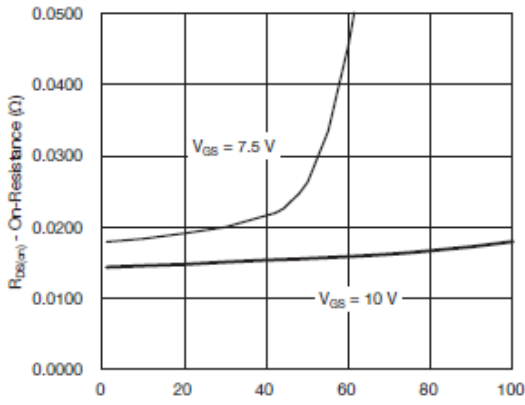
Typical Characteristics



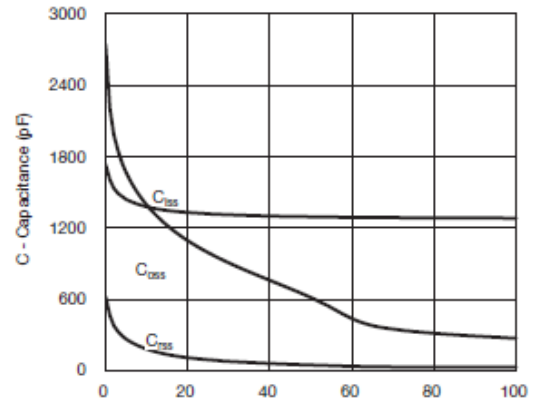
Output Characteristics



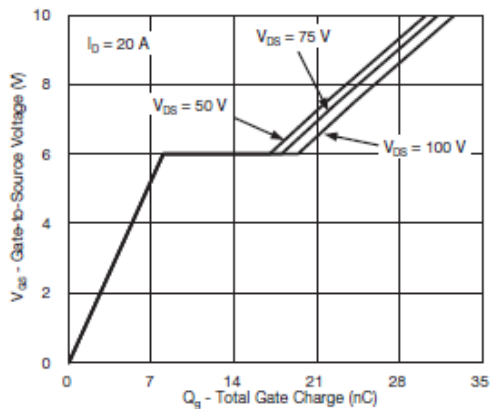
Transfer Characteristics



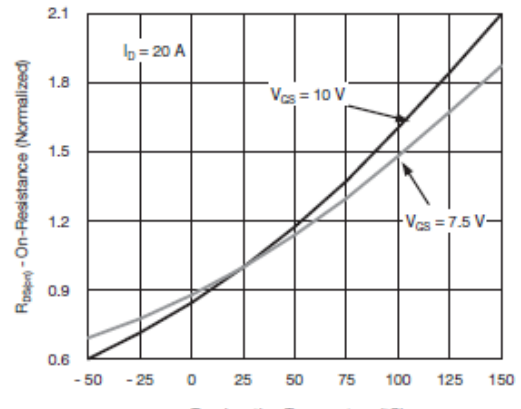
On-Resistance vs. Drain Current



Capacitance



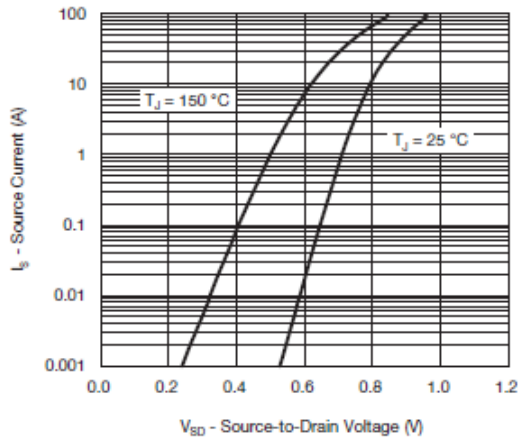
Gate Charge



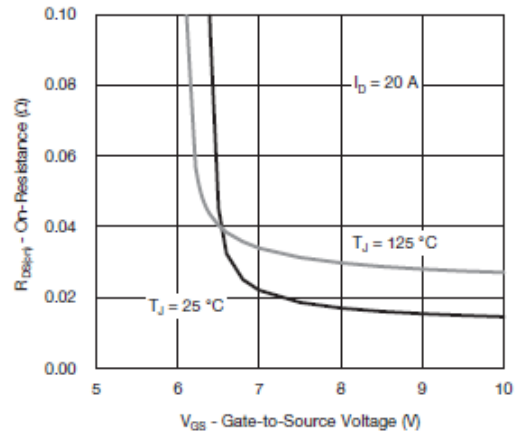
On-Resistance vs. Junction Temperature



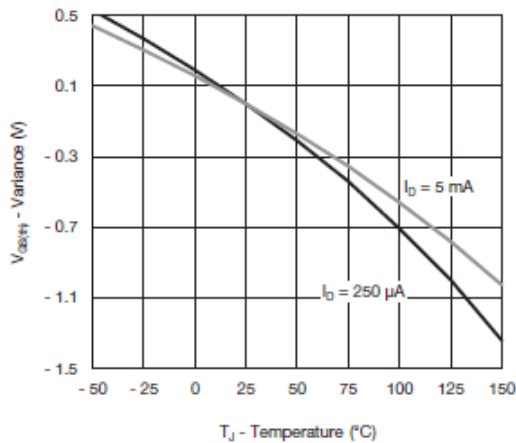
Typical Characteristics



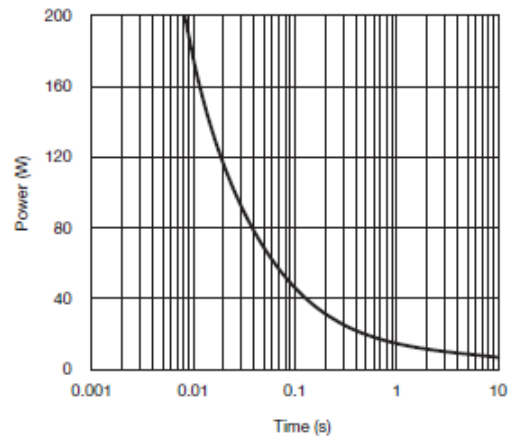
Source-Drain Diode Forward Voltage



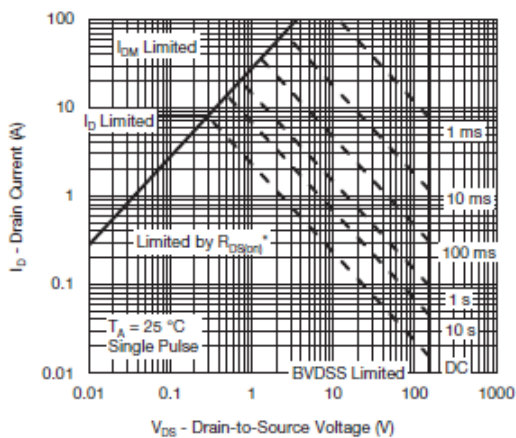
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage

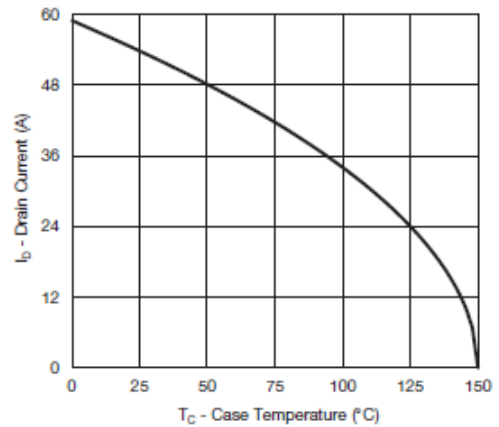


Single Pulse Power, Junction-to-Ambient



* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified

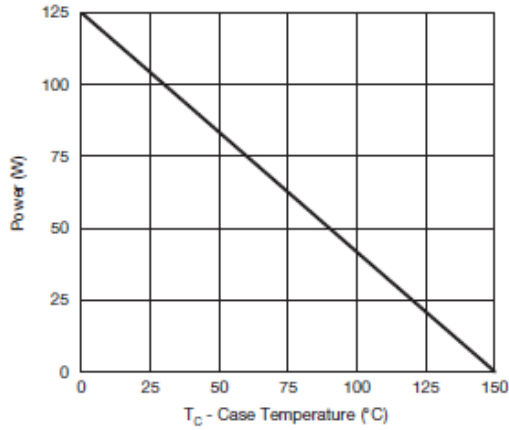
Safe Operating Area, Junction-to-Ambient



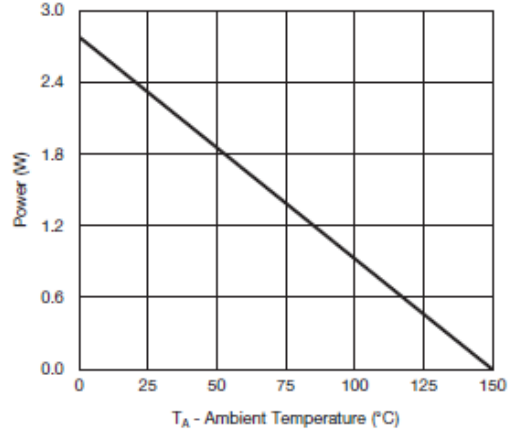
Current Derating*



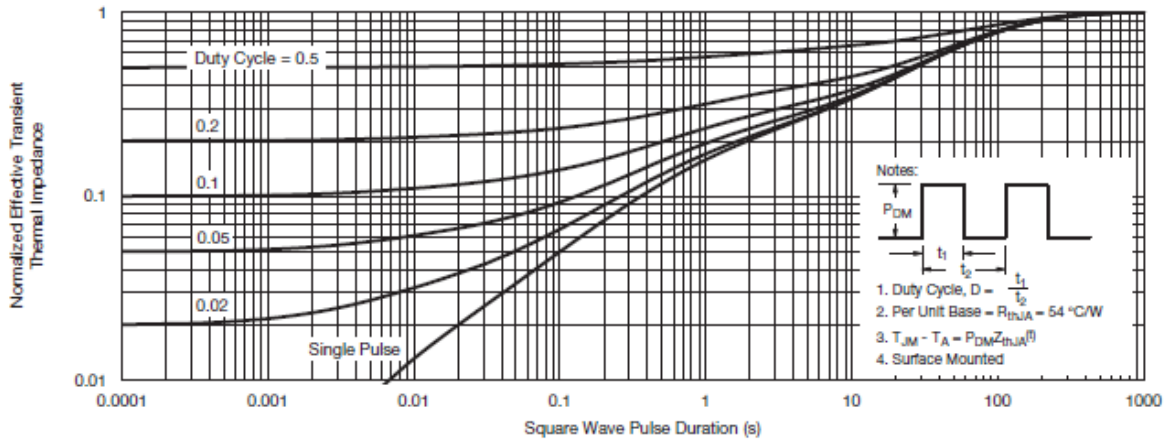
Typical Characteristics



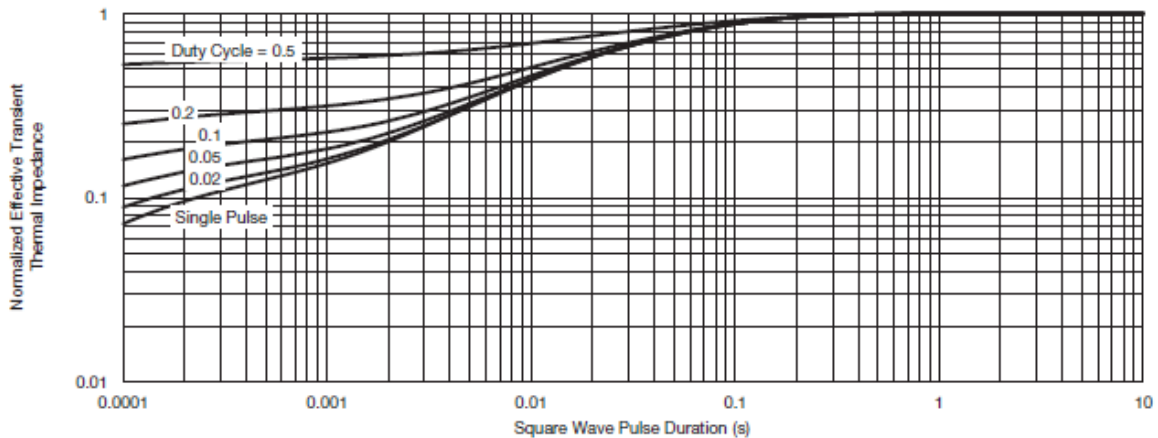
Power, Junction-to-Case



Power, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case



Typical Characteristics

Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms

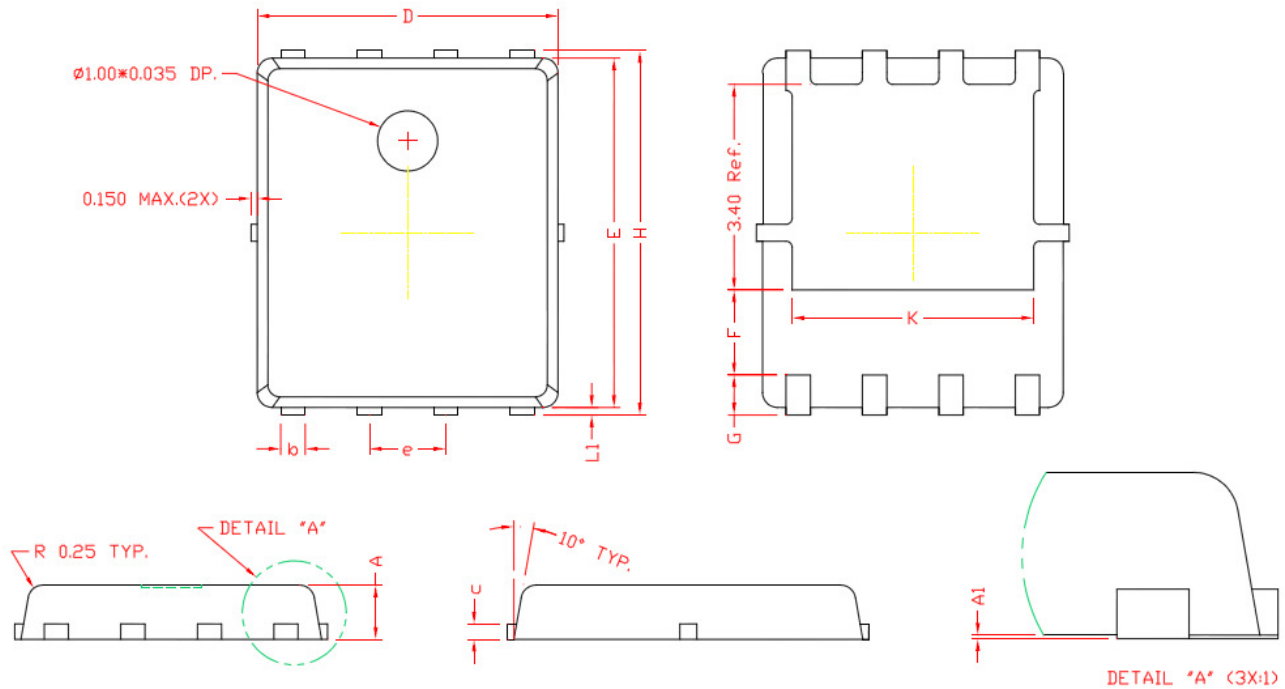


Unclamped Inductive Switching Test Circuit & Waveforms





Package Information (DFN5X6-8L)



DIMENSIONS

REF.	Millimeters		REF.	Millimeters	
	Min.	Max.		Min.	Max.
A	0.80	1.00	E	5.70	5.90
A1	0.00	0.05	e	1.27 BSC.	
b	0.35	0.49	H	5.95	6.20
c	0.254 Ref.		L1	0.10	0.18
D	4.90	5.10	G	0.60 Ref.	
F	1.40 Ref.		K	4.00 Ref.	

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